

# MMBZ15VDLT1, MMBZ27VCLT1

Preferred Devices

## 40 Watt Peak Power Zener Transient Voltage Suppressors

### SOT-23 Dual Common Cathode Zeners for ESD Protection

These dual monolithic silicon zener diodes are designed for applications requiring transient overvoltage protection capability. They are intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment and other applications. Their dual junction common cathode design protects two separate lines using only one package. These devices are ideal for situations where board space is at a premium.

The MMBZ27VCLT1 can be used to protect a single wire communication network from EMI and ESD transient surge voltages. The MMBZ27VCLT1 is recommended by the Society of Automotive Engineers (SAE), February 2000, J2411 "Single Wire Can Network for Vehicle Applications" specification as a solution for transient voltage problems.

#### Specification Features:

- SOT-23 Package Allows Either Two Separate Unidirectional Configurations or a Single Bidirectional Configuration
- Working Peak Reverse Voltage Range - 12.8 V, 22 V
- Standard Zener Breakdown Voltage Range - 15 V, 27 V
- Peak Power - 40 W @ 1.0 ms (Bidirectional), per Figure 5 Waveform
- ESD Rating of Class N (exceeding 16 kV) per the Human Body Model
- Low Leakage < 100 nA
- Flammability Rating: UL 94 V-O
- Pb-Free Packages are Available

#### Mechanical Characteristics:

**CASE:** Void-free, transfer-molded, thermosetting plastic case

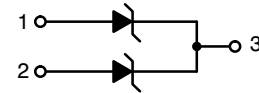
**FINISH:** Corrosion resistant finish, easily solderable

**MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES:**  
260°C for 10 Seconds

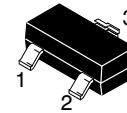


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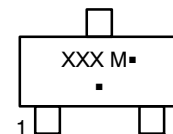


PIN 1. ANODE  
2. ANODE  
3. CATHODE



SOT-23  
CASE 318  
STYLE 9

#### MARKING DIAGRAM



XXX = 15D or 27C  
M = Date Code  
▪ = Pb-Free Package  
(Note: Microdot may be in either location)

#### ORDERING INFORMATION

Device	Package	Shipping†
MMBZ15VDLT1	SOT-23	3000/Tape & Reel
MMBZ15VDLT1G	SOT-23 (Pb-Free)	3000/Tape & Reel
MMBZ15VDLT3	SOT-23	10,000/Tape & Reel
MMBZ15VDLT3G	SOT-23 (Pb-Free)	10,000/Tape & Reel
MMBZ27VCLT1	SOT-23	3000/Tape & Reel
MMBZ27VCLT1G	SOT-23 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

# MMBZ15VDLT1, MMBZ27VCLT1

## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Power Dissipation @ 1.0 ms (Note 1) @ $T_L \leq 25^\circ\text{C}$	$P_{pk}$	40	Watts
Total Power Dissipation on FR-5 Board (Note 2) @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	225 1.8	mW mW/ $^\circ\text{C}$
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Power Dissipation on Alumina Substrate (Note 3) @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	300 2.4	mW mW/ $^\circ\text{C}$
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to +150	$^\circ\text{C}$
Lead Solder Temperature - Maximum (10 Second Duration)	$T_L$	260	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

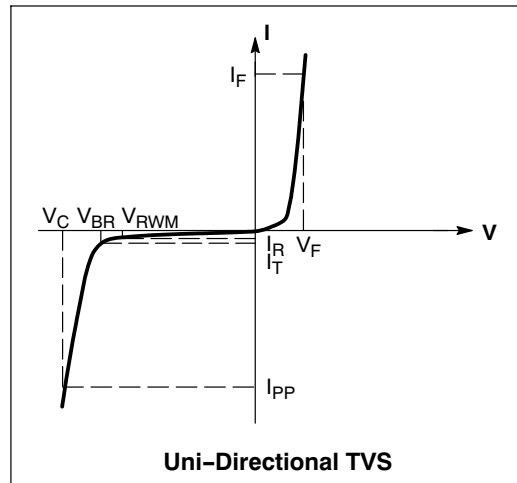
1. Nonrepetitive current pulse per Figure 5 and derate above  $T_A = 25^\circ\text{C}$  per Figure 6.
2. FR-5 =  $1.0 \times 0.75 \times 0.62$  in.
3. Alumina =  $0.4 \times 0.3 \times 0.024$  in., 99.5% alumina

## ELECTRICAL CHARACTERISTICS

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

**UNIDIRECTIONAL** (Circuit tied to Pins 1 and 3 or 2 and 3)

Symbol	Parameter
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current
$V_{BR}$	Maximum Temperature Coefficient of $V_{BR}$
$I_F$	Forward Current
$V_F$	Forward Voltage @ $I_F$



## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

**UNIDIRECTIONAL** (Circuit tied to Pins 1 and 3 or Pins 2 and 3)

( $V_F = 0.9 \text{ V Max @ } I_F = 10 \text{ mA}$ )

Device	Device Marking	$V_{RWM}$ Volts	$I_R @ V_{RWM}$ nA	Breakdown Voltage				$V_C @ I_{PP}$ (Note 5)		$V_{BR}$ mV/ $^\circ\text{C}$
				$V_{BR}$ (Note 4) (V)			@ $I_T$ mA	$V_C$ V	$I_{PP}$ A	
				Min	Nom	Max				
MMBZ15VDLT1, G*	15D	12.8	100	14.3	15	15.8	1.0	21.2	1.9	12

( $V_F = 1.1 \text{ V Max @ } I_F = 200 \text{ mA}$ )

Device	Device Marking	$V_{RWM}$ Volts	$I_R @ V_{RWM}$ nA	Breakdown Voltage				$V_C @ I_{PP}$ (Note 5)		$V_{BR}$ mV/ $^\circ\text{C}$
				$V_{BR}$ (Note 4) (V)			@ $I_T$ mA	$V_C$ V	$I_{PP}$ A	
				Min	Nom	Max				
MMBZ27VCLT1, G*	27C	22	50	25.65	27	28.35	1.0	38	1.0	26

\*The "G" suffix indicates Pb-Free package available.

4.  $V_{BR}$  measured at pulse test current  $I_T$  at an ambient temperature of  $25^\circ\text{C}$ .
5. Surge current waveform per Figure 5 and derate per Figure 6

# MMBZ15VDLT1, MMBZ27VCLT1

## TYPICAL CHARACTERISTICS

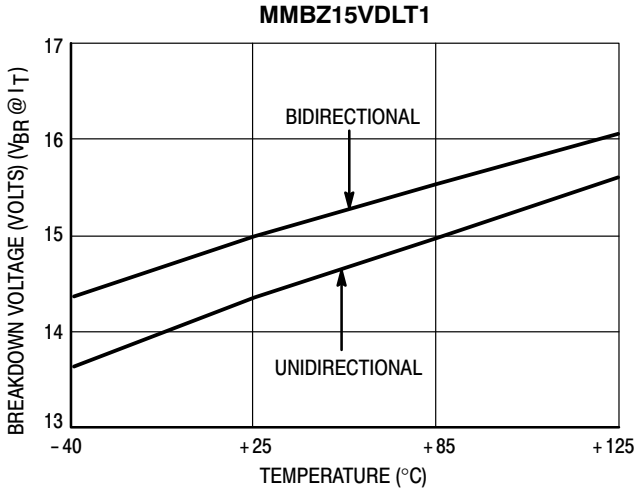


Figure 1. Typical Breakdown Voltage versus Temperature

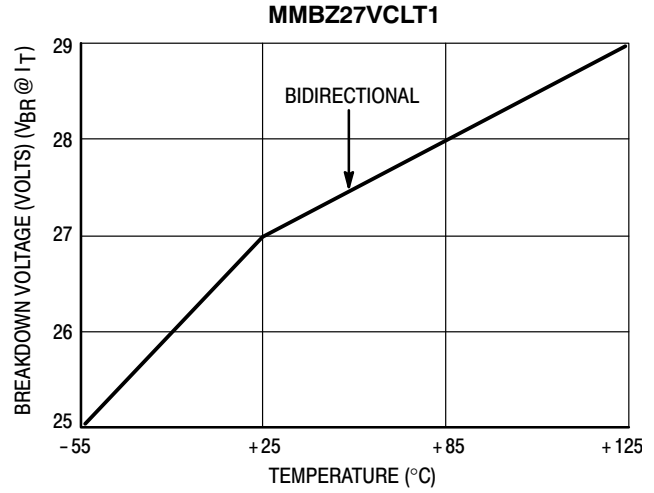


Figure 2. Typical Breakdown Voltage versus Temperature

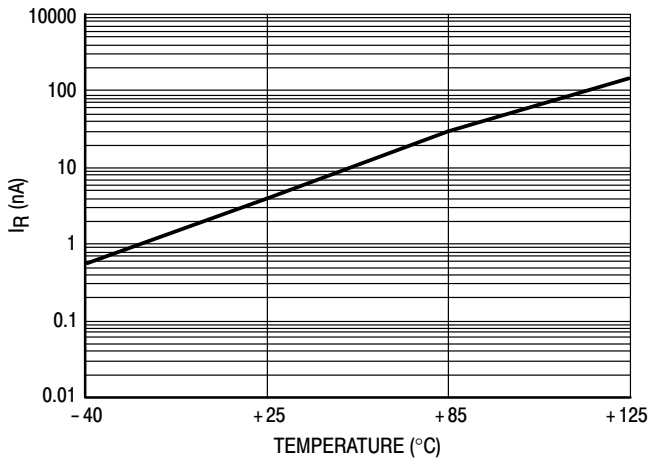


Figure 3. Typical Leakage Current versus Temperature

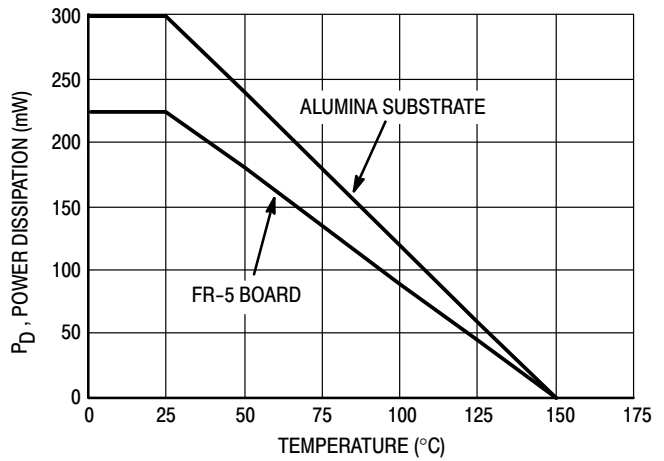


Figure 4. Steady State Power Derating Curve

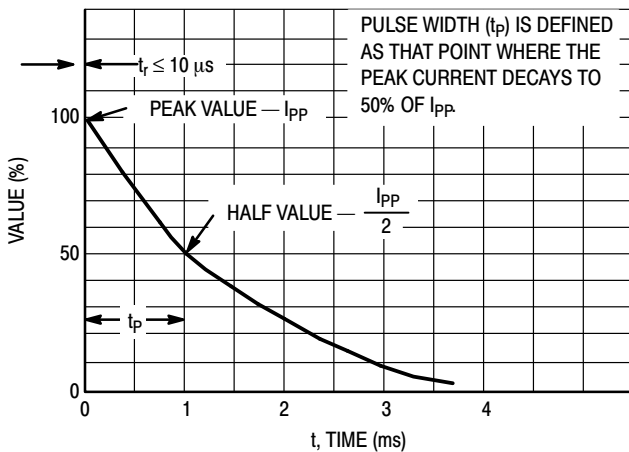


Figure 5. Pulse Waveform

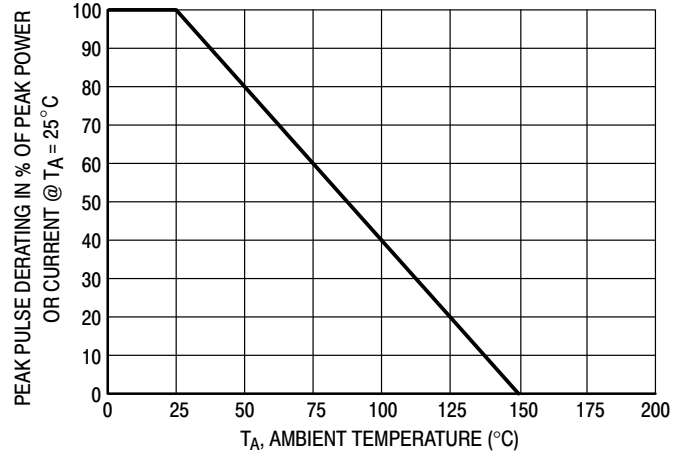
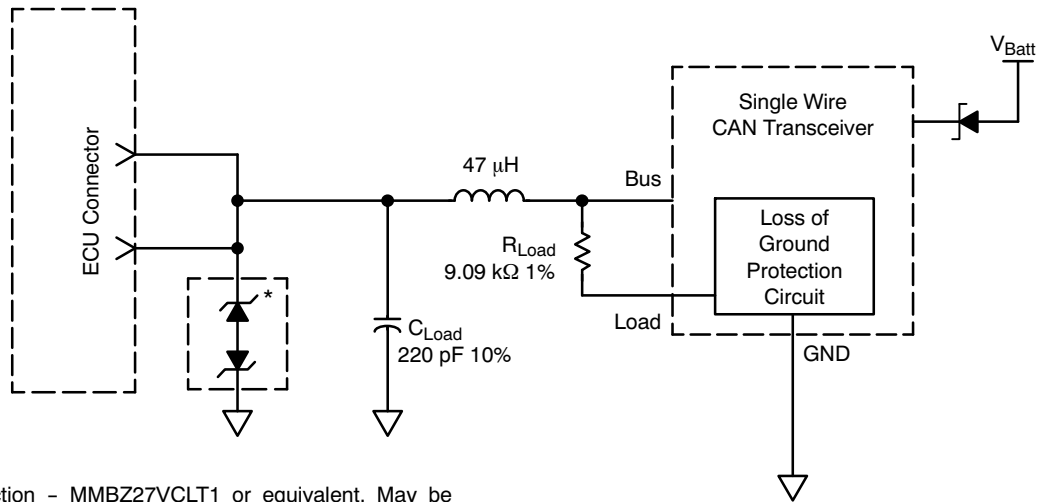


Figure 6. Pulse Derating Curve

# MMBZ15VDLT1, MMBZ27VCLT1

## TYPICAL APPLICATIONS



\*ESD Protection - MMBZ27VCLT1 or equivalent. May be located in each ECU (C<sub>Load</sub> needs to be reduced accordingly) or at a central point near the DLC.

**Figure 7. Single Wire CAN Network**

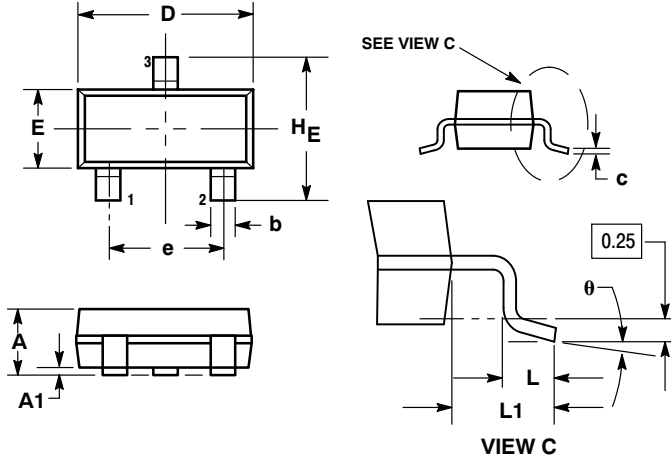
Figure is the recommended solution for transient EMI/ESD protection. This circuit is shown in the Society of Automotive Engineers February, 2000 J2411 “Single Wire CAN Network for Vehicle Applications” specification (Figure 6, page 11). Note: the dual common anode zener configuration shown above is electrically equivalent to a dual common cathode zener configuration.

# MMBZ15VDLT1, MMBZ27VCLT1

## PACKAGE DIMENSIONS

SOT-23 (TO-236)  
CASE 318-08  
ISSUE AN

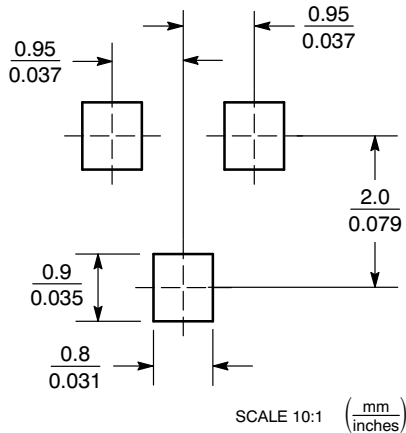
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
  4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

- STYLE 9:  
PIN 1. ANODE  
2. ANODE  
3. CATHODE

## SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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